

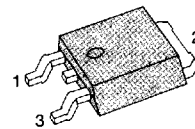
## FEATURES

- Lower  $R_{DS(on)}$
- Excellent voltage stability
- Fast switching speeds
- Rugged polysilicon gate cell structure
- Lower input capacitance
- Extended safe operating area
- Improved high temperature reliability

## PRODUCT SUMMARY

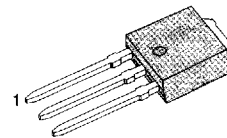
| Part Number  | V <sub>DS</sub> | R <sub>DS(on)</sub> | I <sub>D</sub> |
|--------------|-----------------|---------------------|----------------|
| IRLR014/U014 | 60V             | 0.30 $\Omega$       | 6.7A           |
| IRLR010/U010 | 50V             | 0.30 $\Omega$       | 6.7A           |

**D-PAK**



1.Gate 2.Drain 3.Source  
 IRLR014/010

**I-PAK**



1.Gate 2.Drain 3.Source  
 IRLU014/010

## ABSOLUTE MAXIMUM RATINGS

| Characteristic                                                             | Symbol                            | IRLR014<br>IRLU014 | IRLR010<br>IRLU010 | Unit            |
|----------------------------------------------------------------------------|-----------------------------------|--------------------|--------------------|-----------------|
| Drain-Source Voltage (1)                                                   | V <sub>DSS</sub>                  | 60                 | 50                 | V <sub>dc</sub> |
| Drain-Gate Voltage ( $R_{GS}=1M\Omega$ )(1)                                | V <sub>DGR</sub>                  | 60                 | 50                 | V <sub>dc</sub> |
| Gate-Source Voltage                                                        | V <sub>GS</sub>                   | $\pm 15$           |                    | V <sub>dc</sub> |
| Continuous Drain Current T <sub>C</sub> =25 °C                             | I <sub>D</sub>                    | 6.7                |                    | A <sub>dc</sub> |
| Continuous Drain Current T <sub>C</sub> =100 °C                            | I <sub>D</sub>                    | 4.2                |                    | A <sub>dc</sub> |
| Drain Current - Pulsed (3)                                                 | I <sub>DM</sub>                   | 27                 |                    | A <sub>dc</sub> |
| Total Power Dissipation @ T <sub>C</sub> =25 °C                            | P <sub>D</sub>                    | 25                 |                    | Watts           |
| Derate Above 25 °C                                                         |                                   | 0.20               |                    | W/ °C           |
| Operating and Storage<br>Junction Temperature Range                        | T <sub>J</sub> , T <sub>STG</sub> | -55 to +150        |                    | °C              |
| Maximum Lead Temp. for Soldering<br>Purposes, 1/8" from case for 5 seconds | T <sub>L</sub>                    | 300                |                    | °C              |

Notes : (1) T<sub>J</sub>=25°C to 150°C

(2) Pulse test : Pulse width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$

(3) Repetitive rating : Pulse width limited by junction temperature

**ELECTRICAL CHARACTERISTICS** (T<sub>c</sub>=25°C unless otherwise specified)

| Symbol              | Characteristic                                     | Min | Typ | Max  | Units | Test Conditions                                                                                                                                                     |
|---------------------|----------------------------------------------------|-----|-----|------|-------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| BV <sub>DSS</sub>   | Drain-Source Breakdown Voltage                     |     |     |      |       |                                                                                                                                                                     |
|                     | IRLR014/U014                                       | 60  | -   | -    | V     | V <sub>GS</sub> =0V, I <sub>D</sub> =250μA                                                                                                                          |
|                     | IRLR010/U010                                       | 50  | -   | -    | V     |                                                                                                                                                                     |
| V <sub>GS(th)</sub> | Gate Threshold Voltage                             | 1.0 | -   | 2.0  | V     | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =1mA                                                                                                              |
| I <sub>GSS</sub>    | Gate-Source Leakage Forward                        | -   | -   | 100  | nA    | V <sub>GS</sub> =15V                                                                                                                                                |
| I <sub>GSS</sub>    | Gate-Source Leakage Reverse                        | -   | -   | -100 | nA    | V <sub>GS</sub> =-15V                                                                                                                                               |
| I <sub>DSS</sub>    | Zero Gate Voltage                                  | -   | -   | 250  | μA    | V <sub>DS</sub> =Max. Rating, V <sub>GS</sub> =0V                                                                                                                   |
|                     | Drain Current                                      | -   | -   | 1000 | μA    | V <sub>DS</sub> =0.8 Max. Rating, V <sub>GS</sub> =0V, T <sub>C</sub> =125°C                                                                                        |
| R <sub>DS(on)</sub> | Static Drain-Source On Resistance(2)               | -   | -   | 0.30 | Ω     | V <sub>GS</sub> =5.0V, I <sub>D</sub> =3.4A                                                                                                                         |
| g <sub>fs</sub>     | Forward Transconductance (2)                       | 4.0 | -   | -    | μ     | V <sub>DS</sub> ≥ 15V, I <sub>D</sub> =3.4A                                                                                                                         |
| C <sub>iss</sub>    | Input Capacitance                                  | -   | 400 | -    | pF    | V <sub>GS</sub> =0V, V <sub>DS</sub> =25V, f=1.0MHz                                                                                                                 |
| C <sub>oss</sub>    | Output Capacitance                                 | -   | 150 | -    | pF    |                                                                                                                                                                     |
| C <sub>rss</sub>    | Reverse Transfer Capacitance                       | -   | 50  | -    | pF    |                                                                                                                                                                     |
| t <sub>d(on)</sub>  | Turn-On Delay Time                                 | -   | 12  | 20   | ns    | V <sub>DD</sub> =0.5 BV <sub>DSS</sub> , I <sub>D</sub> =6.7A, Z <sub>Θ</sub> =24Ω<br>(MOSFET switching times are essentially independent of operating temperature) |
| t <sub>r</sub>      | Rise Time                                          | -   | 35  | 50   | ns    |                                                                                                                                                                     |
| t <sub>d(off)</sub> | Turn-Off Delay Time                                | -   | 35  | 50   | ns    |                                                                                                                                                                     |
| t <sub>f</sub>      | Fall Time                                          | -   | 30  | 40   | ns    |                                                                                                                                                                     |
| Q <sub>g</sub>      | Total Gate Charge<br>(Gate-Source Plus Gate-Drain) | -   | -   | 13   | nC    | V <sub>GS</sub> =5V, I <sub>D</sub> =6.7A, V <sub>DS</sub> =0.8 Max. Rating<br>(Gate charge is essentially independent of operating temperature)                    |
| Q <sub>gs</sub>     | Gate-Source Charge                                 | -   | 3.8 | -    | nC    |                                                                                                                                                                     |
| Q <sub>gd</sub>     | Gate-Drain Charge                                  | -   | 4.8 | -    | nC    |                                                                                                                                                                     |

**THERMAL RESISTANCE**

| Symbol            | Characteristics     |     | All | Units | Remark                                     |
|-------------------|---------------------|-----|-----|-------|--------------------------------------------|
| R <sub>thJC</sub> | Junction-to-Case    | MAX | 5.0 | K/W   |                                            |
| R <sub>thCS</sub> | Case-to-Sink        | TYP | 1.7 | K/W   | Mounting surface flat, smooth, and greased |
| R <sub>thJA</sub> | Junction-to-Ambient | MAX | 110 | K/W   | Free Air Operation                         |

Notes : (1) T<sub>J</sub>=25°C to 150°C

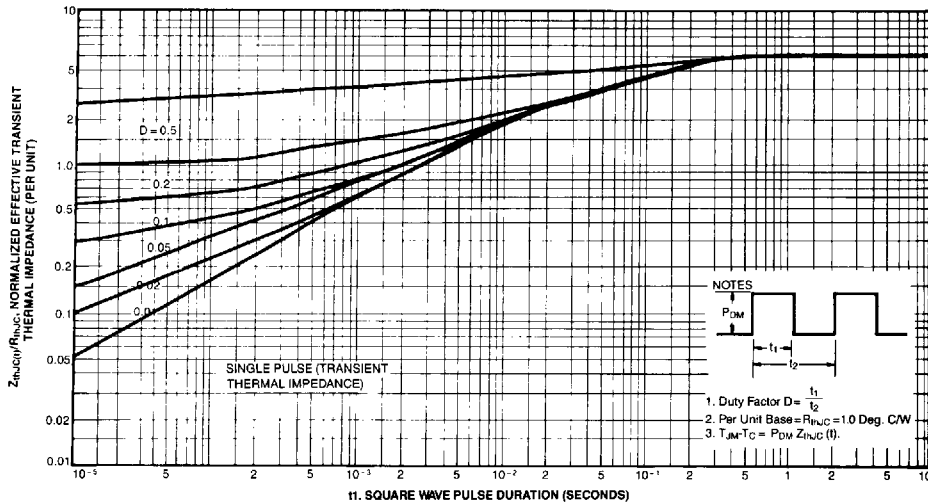
(2) Pulse test : Pulse width ≤ 300μs, Duty Cycle ≤ 2%

(3) Repetitive rating : Pulse width limited by max. junction temperature

# SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

| Symbol   | Characteristic                         | Min | Typ | Max | Units | Test Condition                                                                       |
|----------|----------------------------------------|-----|-----|-----|-------|--------------------------------------------------------------------------------------|
| $I_S$    | Continuous Source Current (Body Diode) | —   | —   | 6.7 | A     | Modified MOSFET symbol showing the integral reverse P-N junction rectifier           |
| $I_{SM}$ | Pulse Source Current (Body Diode) (3)  | —   | —   | 27  | A     |                                                                                      |
| $V_{SD}$ | Diode Forward Voltage (2)              | —   | —   | 1.8 | V     | $T_J = 25^\circ\text{C}$ , $I_S = 6.7\text{A}$ , $V_{GS} = 0\text{V}$                |
| $t_{rr}$ | Reverse Recovery Time                  | —   | —   | 200 | ns    | $T_J = 25^\circ\text{C}$ , $I_F = 6.7\text{A}$ , $dI_F/dt = 100\text{A}/\mu\text{S}$ |

Notes : (1)  $T_J = 25^\circ\text{C}$  to  $150^\circ\text{C}$   
 (2) Pulse test : Pulse width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$   
 (3) Repetitive rating : Pulse width limited by max. junction temperature



MAXIMUM EFFECTIVE TRANSIENT THERMAL IMPEDANCE JUNCTION-TO-CASE  $V_{GS}$ , PULSE DURATION

